Nidec
All for dreams

1H, 2025 Investor Conference

尼得科超眾科技股份有限公司
Nidec Chaun-Choung Technology Corp.

August 29th, 2025

Disclaimer

This presentation of NCCI contains forward-looking statements subject to risks and uncertainties. Actual results may differ materially from the contained in the forward-looking statements.

The forward-looking statements in this presentation are the current belief of NCCI as of the date for this release, and NCCI has no obligation to update the forward-looking statements for new information, future events, or otherwise.

Agenda

- **Company Profile**
- **Focus: Market, Products & Technologies**
- **1H, 2025 Financial Results**
- **Q & A**

Company Profile

- **Chairman and CEO**：Miyoshi Akihiro
- **Founded :** Dec.14. 1973
- **Stock Listing**：TWSE (ticker: 6230)
- **Nidec Corporation:**

  Hold 86.30% shares, as a major shareholder (Jul. 2025).
- **Capital :** NT$ 863,434 (K)
- **HQ Address :** No. 184-3, Zhongxing N. St., Sanchong Dist.,

  New Taipei City 241, Taiwan
- **Main Business :** Heat Sink & Thermal Solutions
- **WW Factories & Offices**

Worldwide Factories & Offices

Nidec Chaun Choung - Core Competitiveness

1

Professional Thermal Team & Innovation

Our team has expertise in thermal design, material development, and process optimization.
We develop Heat Pipes, Vapor Chambers, 3D VCs, ultra-thin pipes, and liquid cooling modules.
We work with global customers to address AI and HPC thermal challenges.

2

Group Resource Integration & Global Deployment

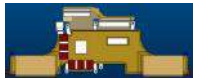
We co-develop fans and liquid cooling components with Nidec Group.
We have manufacturing bases in Taiwan, Kunshan, and Chongqing.
We provide large-scale production with complete process and testing capabilities

3

Market-Oriented Portfolio & Customization

Our products cover from 10W notebooks to 10kW AI server. We mass produce Slim VC, 3D VC, ultra-long pipes, and large-diameter pipes. Our roadmap is aligned with AI, HPC, and server market growth.

Focus Market

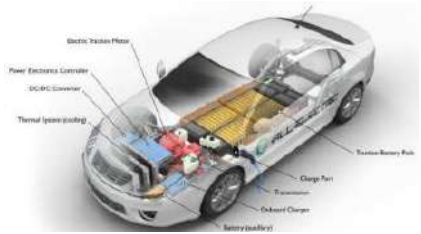











5G : Network/Telecom

PC : NB/DT

HPC
(High-Performance Computing)

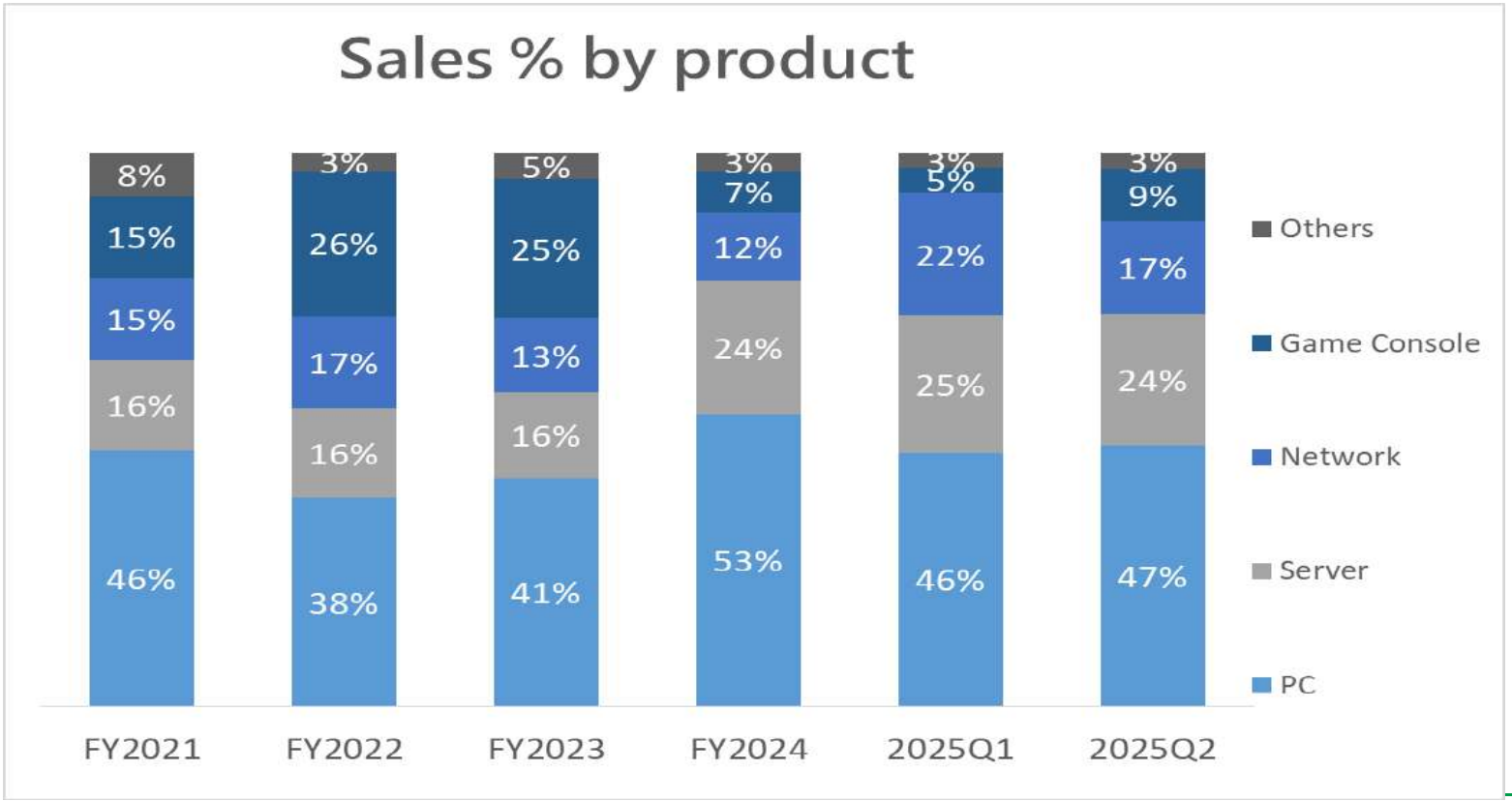
Heat Transfer Core Technology

Automotive(EV)

Gaming

Portable Devices

Business Performance



NCCI Product Line-up for Thermal Solutions

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Heat Load/Unit

100 kw

10 kw

1 kw

100 w

10 w

Nidec

Liquid to Air

Liquid to Liquid

LCM

Nidec NCCI

NCCI

Thin HP/VC w/ Fan

Ultra Thin HP/VC

HP/VC module w/ Fan

HP/VC Module

3D VC

Tablet/Laptop | Console/Desktop | Workstation | Server | Data Center

Application：Notebook/Desktop PC

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Now

Future

Thermal Solution for AI Laptop
D6/D8 Heat pipe Solution CPU+GPU 25~60 Watts

Big diameter Heat pipe for CPU & GPU
Heat pipe diameter：6mm ➔ 10mm

Thermal Solution for AI Laptop
D10 Heat pipe Solution CPU+GPU 25~80 Watts

Thermal Solution for Gaming Laptop
Slim VC (1.4mm≤ t ≤2.5mm) CPU+GPU 90~220 Watts

Slim VC Solution for CPU & GPU
VC thickness：1.4mm ➔ 1.2mm

Thermal Solution for Gaming Laptop
Slim VC (1.2mm≤ t ≤3.0mm) CPU+GPU 90~280 Watts

Thermal Solution for AIO & Desk Top Laptop
D6/D8 Heat pipe Solution CPU+GPU 35~65 Watts

Big diameter Heat pipe for CPU & GPU
Heat pipe diameter：8mm ➔ 12mm

Thermal Solution for AIO & Desk Top Laptop
D10/D12 Heat pipe Solution CPU+GPU 35~95 Watts

Application：Server

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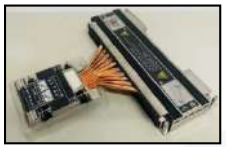
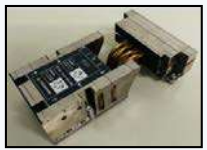
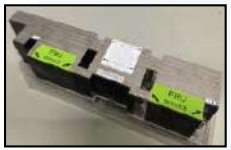
Now



One CPU solution: 500W
Heat pipe length < 400mm



D8 Heat pipe, CPU<600W



GPU=700W

Future

Long Heat pipe for Cloud Server

CPU solution : 500W ➔ 1000W
Heat pipe length : 400mm ➔ 600mm

Two CPU solution : Total 1000W
Heat pipe length > 600mm

Big diameter Heat pipe for Next generation server CPU

CPU solution : 600W ➔ 700W
Heat pipe diameter : 8mm ➔ 10mm

D10 Heat pipe, CPU>700W

Hi-Power 3D VC Thermal Solution for AI Server

High power : 700W ➔ 1000W

GPU>1200W

Application：Network/Telecom

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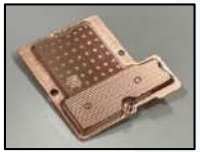
Now

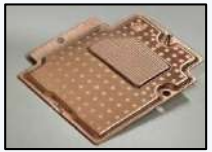

430 W HP solution


500 W HP solution

Hi-Power Air Cooling Solution for Switch

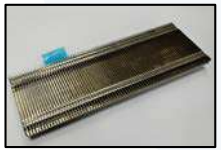
Heatpipe/VC module : 400W ➔ 850W


103 W


152 W

VC Solution for Radio Base Station Product

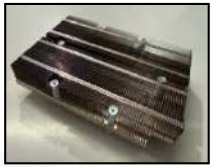
VC : 100W ➔ 255W


13 W

VC Solution for Network Card

VC : 10W ➔ 25W

Future




850 W VC solution


225 W


23 W

NCCI High Power Thermal Solution Roadmap(A/C)

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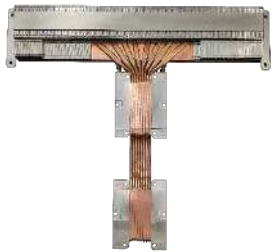
2U

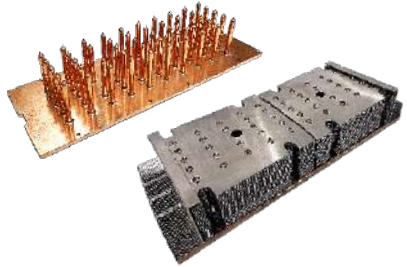
1U

D8 HP Module
200 ~ 450 Watts

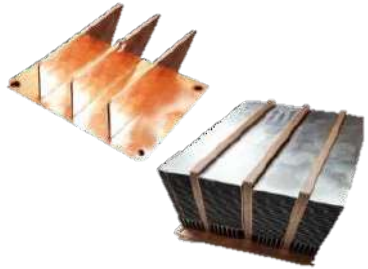


VC Module
600 ~850 Watts

3D VC
1,000 ~1,400 Watts



3D VC Fin
800 ~1,000 Watts



2024 2025 2026 2027 2028

Liquid Cooling Products

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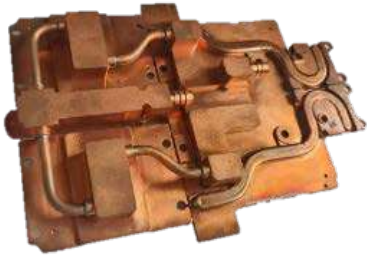
GPU & CPU LCM Engineering Testing Fixture

CPU LCM & Standard Cold plate

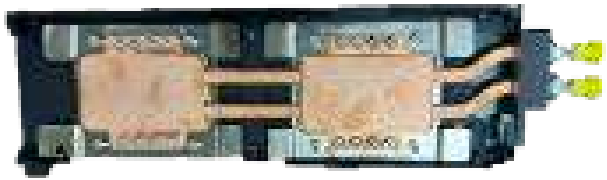
Intel CPU		AMD CPU
EGS 350W	BHS SP 350W	Milan SP3 225W
• R :0.027°C/W • ΔP: 2.77kPa	• R :0.031°C/W • 2.75 kPa	• R :0.032°C/W • ΔP: 3.22 kPa
Whitley 280W	BHS AP 500W	Genoa SP5 500W
• R :0.039°C/W • ΔP: 2.95 kPa	• R :0.024°C/W • ΔP: 3.42 kPa	• R :0.025°C/W • ΔP: 2.75 kPa

Inner Manifold

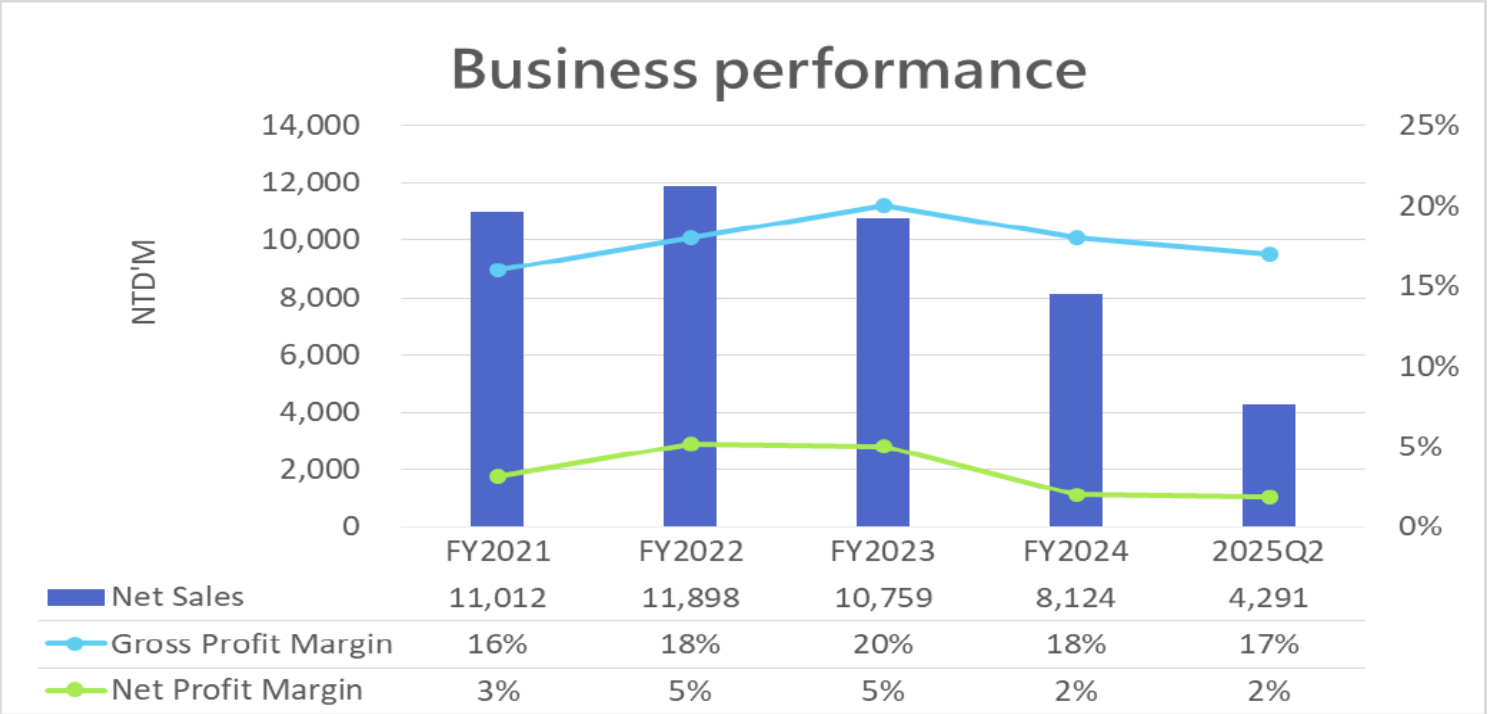
CPU LCM



ASIC & PCIE LCM



Business Performance



FY / NTD	2021	2022	2023	2024	2025Q2
EPS	4.05	7.10	7.02	1.48	0.80

Q & A

2025/08/29